PCN Number:	20161115003			PCN Date:		e:	Jan. 4, 2017		
Title: Datasheet for	SN54HC541, SN74HC541						,		
Customer Contact:	PCN Manager				Dept:		Quality Services	5	
Change Type:									
Assembly Site		Des	ign			Wafe	r Bump Site		
Assembly Process		⊠ Data				Wafer Bump Material			
Assembly Materials		_	number change				fer Bump Process		
Mechanical Specification		=	t Site		Щ		r Fab Site		
Packing/Shipping/Labeling		Tes	t Process		Щ.		r Fab Materials		
		- +:C: -	- 4' D - 4 - 'I -			Wafe	r Fab Process		
Description of Change		OTITIC	ation Details	<u> </u>					
Description of Change: Texas Instruments Incorp		uncino	an information	only r	otifi	cation	etc		
The product datasheet(s)					iotiii	Cation	etc.		
The following change hist				,,,,					
_	, p								
TEXAS					SN	154HC54	1, SN74HC541		
Instruments			SCLS305	5D – JANU			SEPTEMBER 2016		
Changes from Revision C (Aug	Changes from Revision C (August 2003) to Revision D								
Added Applications section, 1	Added Applications section, Thermal Information table, ESD Ratings table, Feature Description section, Device								
Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout									
section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section 1									
Deleted Ordering Information table, see Mechanical, Packaging, and Orderable Information at the end of the datasheet 1 Changed Buy for DB package from 70°C/W; to 90.2°C/W.									
Changed R _{BJA} for DB package from 70°C/W: to 90.2°C/W									
	Changed R _{BJA} for DW package from 58°C/W: to 77.5°C/W Changed R _{BJA} for N package from 69°C/W: to 45.2°C/W								
_	Changed R _{8,IA} for NS package from 69°C/W: to 45.2°C/W Changed R _{8,IA} for NS package from 60°C/W: to 72.8°C/W								
Changed R _{BJA} for PW package from 83°C/W: to 98.3°C/W									
The datasheet number wi	ll be changing					_			
Device Family		Change From:				Change To:			
SN54HC541, SN74HC541		SCLS305C				SCLS305D			
These changes may be re			ieet links provide	ed.					
http://www.ti.com/produc	ct/SN54HC541								
Reason for Change:									
To more accurately reflect									
Anticipated impact on						_			
No anticipated impact. Th	is is a specific	ation c	hange announce	ment	only	. Ther	e are no changes	to	
the actual device.									
Changes to product ide	entification re	esultin	g from this PC	N:					
None.									
Product Affected:									
JM38510/65711BRA S	N74HC541DWE	4	SN74HC541N		SN	174HC5	41PWR	_	
M38510/65711BRA S	N74HC541DWG	4	SN74HC541NE4		SN	174HC5	41PWRG4]	
SN54HC541J S	N74HC541DWR		SN74HC541NSR		SN	174HC5	41PWT		
SN74HC541DBR S	N74HC541DWR	E4	SN74HC541PW		SN	IJ54HC	541FK		
SN74HC541DW S	N74HC541DWR	G4	SN74HC541PWG	4	SN	1154HC	5/11	1	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com